

Document Title**128Kx8 bit Low Power CMOS Static RAM****Revision History**

<u>Revision No.</u>	<u>History</u>	<u>Draft Data</u>	<u>Remark</u>
0.0	Design target	October 12, 1998	Preliminary
1.0	Finalize - Improve twp form 55ns to 50ns for 70ns product. - Remove 55ns speed bin from industrial product.	August 30, 1999	Final
1.01	Errata correction	December 1, 1999	
2.0	Revise	February 14, 2000	Final
3.0	Revise - Add 55ns parts to industrial products.	March 3, 2000	Final

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128Kx8 bit Low Power CMOS Static RAM

FEATURES

- Process Technology: TFT
- Organization: 128Kx8
- Power Supply Voltage: 4.5–5.5V
- Low Data Retention Voltage: 2V(Min)
- Three state output and TTL Compatible
- Package Type: 32-DIP-600, 32-SOP-525, 32-TSOP1-0820F/R

GENERAL DESCRIPTION

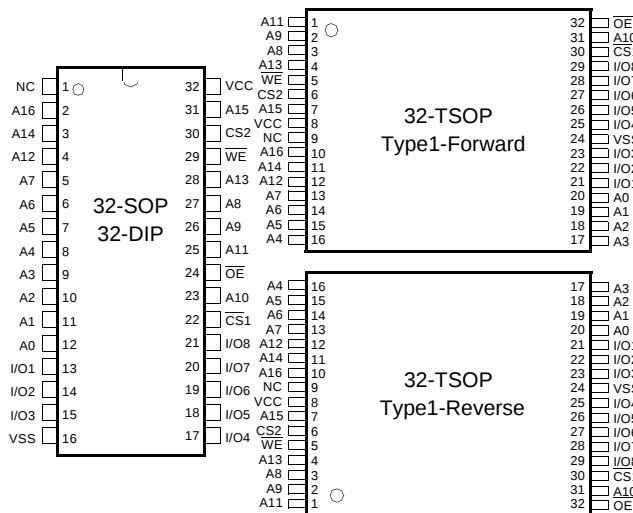
The K6T1008C2E families are fabricated by SAMSUNG's advanced CMOS process technology. The families support various operating temperature ranges and have various package types for user flexibility of system design. The families also support low data retention voltage for battery back-up operation with low data retention current.

PRODUCT FAMILY

Product Family	Operating Temperature	Vcc Range	Speed	Power Dissipation		PKG Type
				Standby (I _{SB1} , Max)	Operating (I _{CC2} , Max)	
K6T1008C2E-L	Commercial(0~70°C)	4.5~5.5V	55 ¹ /70ns	50μA	50mA	32-DIP-600, 32-SOP-525 32-TSOP1-0820F/R
K6T1008C2E-B				10μA		
K6T1008C2E-P	Industrial(-40~85°C)			50μA		32-SOP-525 32-TSOP1-0820F/R
K6T1008C2E-F				15μA		

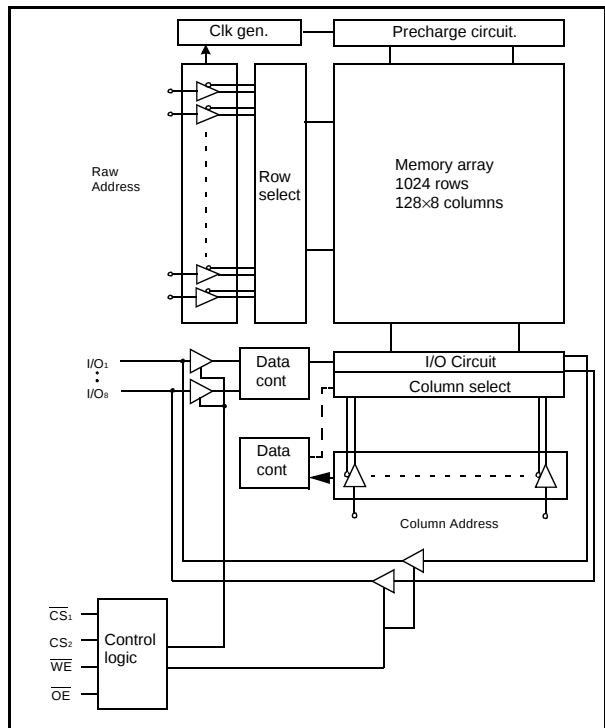
1. The parameters are tested with 50pF test load

PIN DESCRIPTION



Name	Function
$\overline{CS}_1, \overline{CS}_2$	Chip Select Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
I/O1~I/O8	Data Inputs/Outputs
A0~A16	Address Inputs
Vcc	Power
Vss	Ground
NC	No Connection

FUNCTIONAL BLOCK DIAGRAM



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PRODUCT LIST

Commercial Temperature Products(0~70°C)		Industrial Temperature Products(-40~85°C)	
Part Name	Function	Part Name	Function
K6T1008C2E-DL55	32-DIP, 55ns, Low Power	K6T1008C2E-GP55	32-SOP, 55ns, Low Power
K6T1008C2E-DL70	32-DIP, 70ns, Low Power	K6T1008C2E-GP70	32-SOP, 70ns, Low Power
K6T1008C2E-DB55	32-DIP, 55ns, Low Low Power	K6T1008C2E-GF55	32-SOP, 55ns, Low Low Power
K6T1008C2E-DB70	32-DIP, 70ns, Low Low Power	K6T1008C2E-GF70	32-SOP, 70ns, Low Low Power
K6T1008C2E-GL55	32-SOP, 55ns, Low Power	K6T1008C2E-TF55	32-TSOP-F, 55ns, Low Low Power
K6T1008C2E-GL70	32-SOP, 70ns, Low Power	K6T1008C2E-TF70	32-TSOP-F, 70ns, Low Low Power
K6T1008C2E-GB55	32-SOP, 55ns, Low Low Power	K6T1008C2E-RF55	32-TSOP-R, 55ns, Low Low Power
K6T1008C2E-GB70	32-SOP, 70ns, Low Low Power	K6T1008C2E-RF70	32-TSOP-R, 70ns, Low Low Power
K6T1008C2E-TB55	32-TSOP-F, 55ns, Low Low Power		
K6T1008C2E-TB70	32-TSOP-F, 70ns, Low Low Power		
K6T1008C2E-RB55	32-TSOP-R, 55ns, Low Low Power		
K6T1008C2E-RB70	32-TSOP-R, 70ns, Low Low Power		

FUNCTIONAL DESCRIPTION

$\overline{CS}_1$	CS_2	$\overline{OE}$	$\overline{WE}$	I/O	Mode	Power
H	X ¹⁾	X ¹⁾	X ¹⁾	High-Z	Deselected	Standby
X ¹⁾	L	X ¹⁾	X ¹⁾	High-Z	Deselected	Standby
L	H	H	H	High-Z	Output Disabled	Active
L	H	L	H	Dout	Read	Active
L	H	X ¹⁾	L	Din	Write	Active

1. X means don't care (Must be in high or low states)

ABSOLUTE MAXIMUM RATINGS¹⁾

Item	Symbol	Ratings	Unit	Remark
Voltage on any pin relative to Vss	V _{IN} , V _{OUT}	-0.5 to 7.0	V	-
Voltage on Vcc supply relative to Vss	V _{CC}	-0.5 to 7.0	V	-
Power Dissipation	P _D	1.0	W	-
Storage temperature	T _{STG}	-65 to 150	°C	-
Operating Temperature	T _A	0 to 70	°C	K6T1008C2E-L/-B
		-40 to 85	°C	K6T1008C2E-P/-F

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS¹⁾

Item	Symbol	Product	Min	Typ	Max	Unit
Supply voltage	V _{CC}	K6T1008C2E Family	4.5	5.0	5.5	V
Ground	V _{SS}	All Family	0	0	0	V
Input high voltage	V _{IH}	K6T1008C2E Family	2.2	-	V _{CC} +0.5 ²⁾	V
Input low voltage	V _{IL}	K6T1008C2E Family	-0.5 ³⁾	-	0.8	V

Note:

1. Commercial Product: T_A=0 to 70°CIndustrial Product: T_A=-40 to 85°C, otherwise specified.2. Overshoot: V_{CC}+3.0V in case of pulse width≤30ns.

3. Undershoot: -3.0V in case of pulse width≤30ns.

4. Overshoot and undershoot are sampled, not 100% tested.

CAPACITANCE¹⁾ (f=1MHz, T_A=25°C)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C _{IN}	V _{IN} =0V	-	6	pF
Input/Output capacitance	C _{IO}	V _{IO} =0V	-	8	pF

1. Capacitance is sampled, not 100% tested

DC AND OPERATING CHARACTERISTICS

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Input leakage current	I _{LI}	V _{IN} =V _{SS} to V _{CC}	-1	-	1	μA
Output leakage current	I _{LO}	$\overline{CS_1}$ =V _{IH} or CS ₂ =V _{IL} or $\overline{OE}$ =V _{IH} or $\overline{WE}$ =V _{IL} , V _{IO} =V _{SS} to V _{CC}	-1	-	1	μA
Operating power supply current	I _{CC}	I _{IO} =0mA, $\overline{CS_1}$ =V _{IL} , CS ₂ =V _{IH} , V _{IN} =V _{IH} or V _{IL} , Read	-	-	10	mA
Average operating current	I _{CC1}	Cycle time=1μs, 100%duty, I _{IO} =0mA, $\overline{CS_1}$ ≤0.2V, CS ₂ ≥V _{CC} -0.2V, V _{IN} ≤0.2V or V _{IN} ≥V _{CC} -0.2V	-	-	7	mA
	I _{CC2}	Cycle time=Min, 100% duty, I _{IO} =0mA, $\overline{CS_1}$ =V _{IL} , CS ₂ =V _{IH} , V _{IN} =V _{IH} or V _{IL}	-	-	50	mA
Output low voltage	V _{OL}	I _{OL} =2.1mA	-	-	0.4	V
Output high voltage	V _{OH}	I _{OH} =-1.0mA	2.4	-	-	V
Standby Current(TTL)	I _{SB}	$\overline{CS_1}$ =V _{IH} , CS ₂ =V _{IL} , Other inputs=V _{IH} or V _{IL}	-	-	3	mA
Standby Current(CMOS)	I _{SB1}	$\overline{CS_1}$ ≥V _{CC} -0.2V, CS ₂ ≥V _{CC} -0.2V or CS ₂ ≤0.2V, Other inputs=0~V _{CC}	-	-	50 ¹⁾	μA

1. 50μA for Low power product, in case of Low Low power products are comercial=10μA, industrial=15μA.

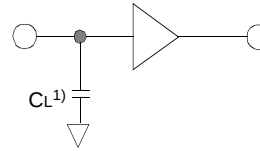
AC OPERATING CONDITIONS

TEST CONDITIONS (Test Load and Input/Output Reference)

Input pulse level: 0.8 to 2.4V

Input rising and falling time: 5ns

Input and output reference voltage: 1.5V

Output load (see right): $C_L = 100\text{pF} + 1\text{TTL}$
 $C_L = 50\text{pF} + 1\text{TTL}$ 

1. Including scope and jig capacitance

AC CHARACTERISTICS ($V_{CC} = 4.5 \sim 5.5\text{V}$, Commercial Product: $T_A = 0$ to 70°C , Industrial Product: $T_A = -40$ to 85°C)

Parameter List		Symbol	Speed Bins				Units
			55ns		70ns		
			Min	Max	Min	Max	
Read	Read Cycle Time	t _{RC}	55	-	70	-	ns
	Address Access Time	t _{AA}	-	55	-	70	ns
	Chip Select to Output	t _{CO}	-	55	-	70	ns
	Output Enable to Valid Output	t _{OE}	-	25	-	35	ns
	Chip Select to Low-Z Output	t _{LZ}	10	-	10	-	ns
	Output Enable to Low-Z Output	t _{OLZ}	5	-	5	-	ns
	Chip Disable to High-Z Output	t _{HZ}	0	20	0	25	ns
	Output Disable to High-Z Output	t _{OHZ}	0	20	0	25	ns
	Output Hold from Address Change	t _{OH}	10	-	10	-	ns
Write	Write Cycle Time	t _{WC}	55	-	70	-	ns
	Chip Select to End of Write	t _{CW}	45	-	60	-	ns
	Address Set-up Time	t _{AS}	0	-	0	-	ns
	Address Valid to End of Write	t _{AW}	45	-	60	-	ns
	Write Pulse Width	t _{WP}	40	-	50	-	ns
	Write Recovery Time	t _{WR}	0	-	0	-	ns
	Write to Output High-Z	t _{WHZ}	0	20	0	25	ns
	Data to Write Time Overlap	t _{DW}	20	-	25	-	ns
	Data Hold from Write Time	t _{DH}	0	-	0	-	ns
	End Write to Output Low-Z	t _{OW}	5	-	5	-	ns

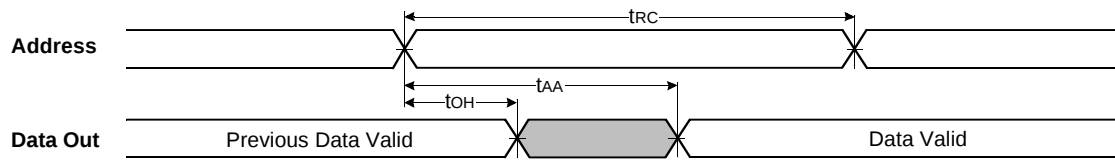
DATA RETENTION CHARACTERISTICS

Item	Symbol	Test Condition	Min	Typ	Max	Unit
V _{CC} for data retention	V _{DR}	$\overline{CS}_1 \geq V_{CC} - 0.2V^{(1)}$	2.0	-	5.5	V
Data retention current	I _{DR}	$V_{CC} = 3.0V, \overline{CS}_1 \geq V_{CC} - 0.2V^{(1)}$	K6T1008C2E-L	-	-	20
			K6T1008C2E-B	-	-	10
			K6T1008C2E-P	-	-	25
			K6T1008C2F-F	-	-	10
Data retention set-up time	t _{SDR}	See data retention waveform	0	-	-	ms
Recovery time	t _{RDR}		5	-	-	

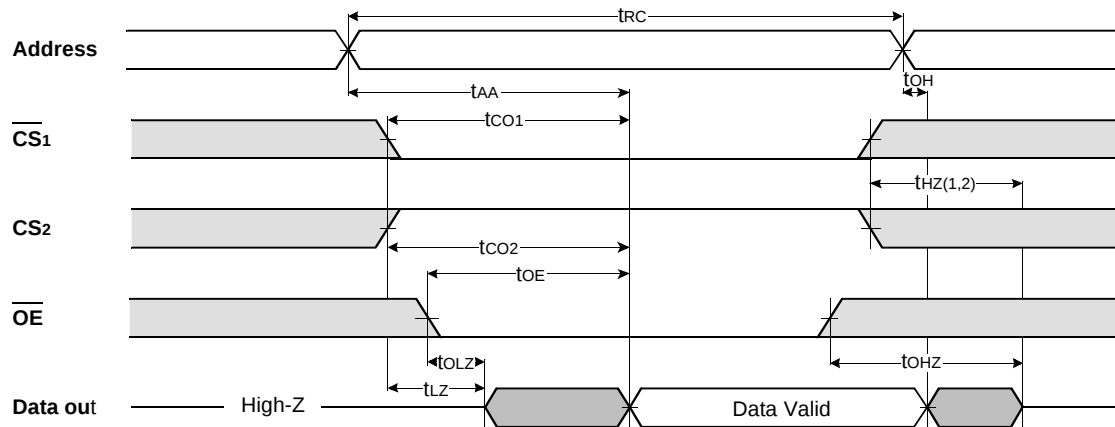
1. $\overline{CS}_1 \geq V_{CC} - 0.2V$, $\overline{CS}_2 \geq V_{CC} - 0.2V$ ($\overline{CS}_1$ controlled) or $\overline{CS}_2 \leq 0.2V$ ($\overline{CS}_2$ controlled)

TIMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, $\overline{CS1}=\overline{OE}=V_{IL}$, $CS2=\overline{WE}=V_{IH}$)

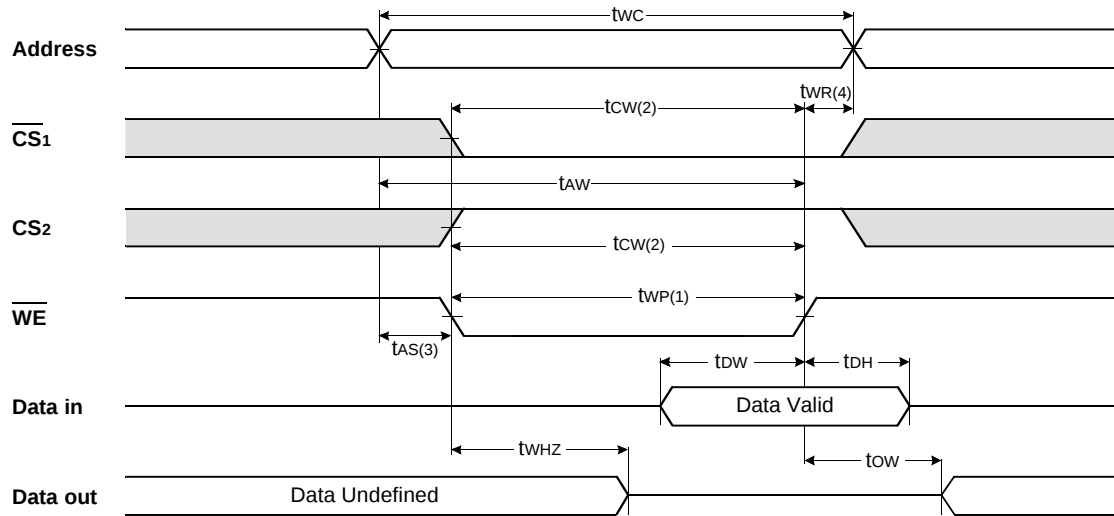
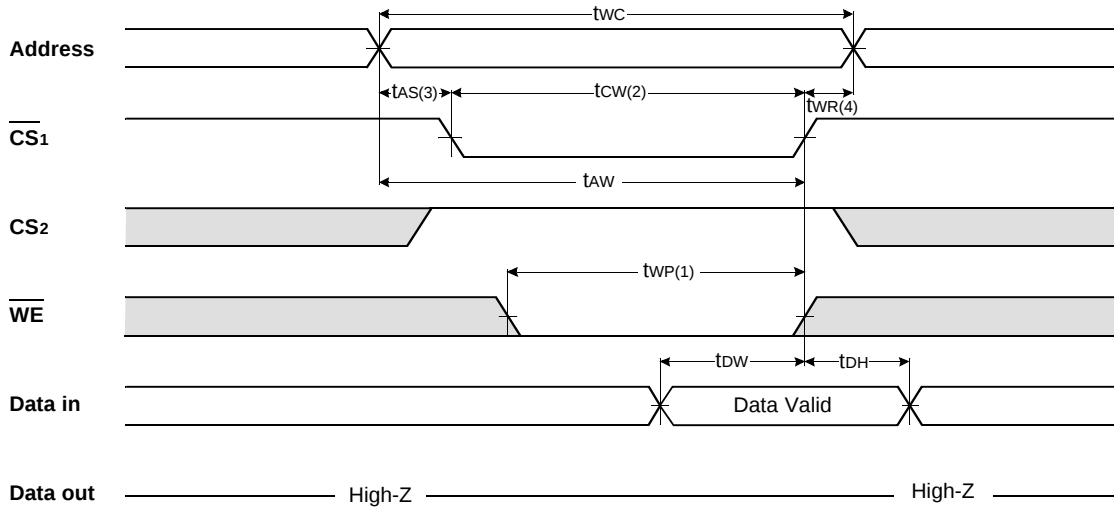


TIMING WAVEFORM OF READ CYCLE(2) ($\overline{WE}=V_{IH}$)

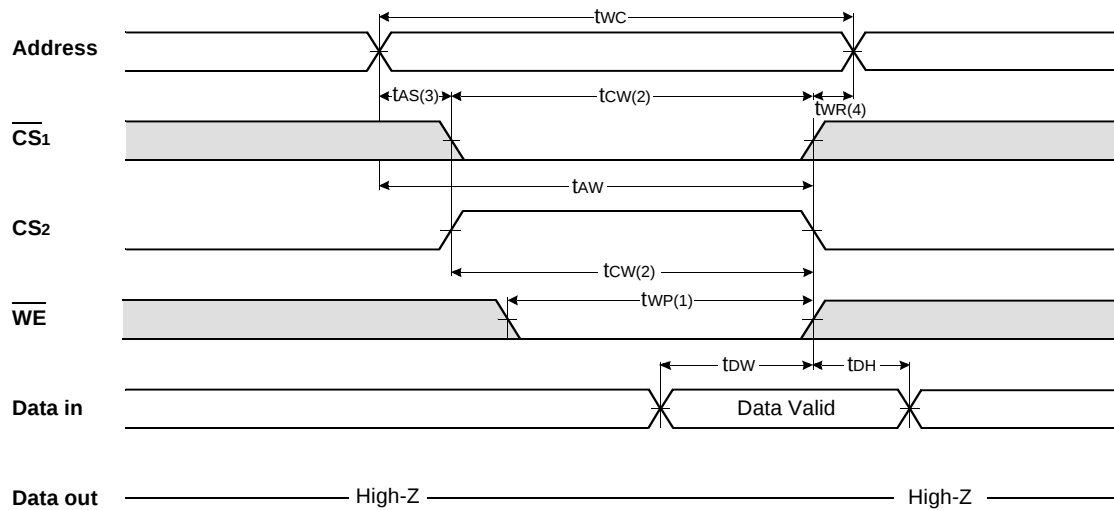


NOTES (READ CYCLE)

1. t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, $t_{HZ}(\text{Max.})$ is less than $t_{LZ}(\text{Min.})$ both for a given device and from device to device interconnection.

TIMING WAVEFORM OF WRITE CYCLE(1) ($\overline{\text{WE}}$ Controlled)TIMING WAVEFORM OF WRITE CYCLE(2) ($\overline{\text{CS1}}$ Controlled)

TIMING WAVEFORM OF WRITE CYCLE(3) (CS₂ Controlled)

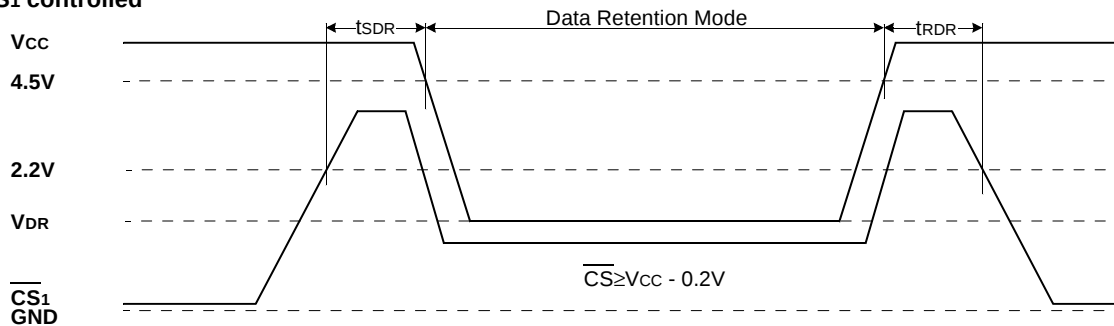


NOTES (WRITE CYCLE)

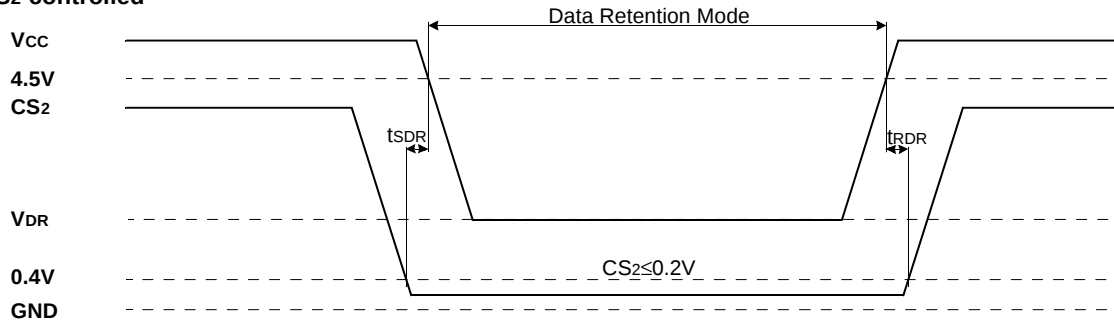
1. A write occurs during the overlap of a low $\overline{CS_1}$, a high CS₂ and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS_1}$ goes low, CS₂ going high and WE going low: A write ends at the earliest transition among CS₁ going high, CS₂ going low and WE going high, tWP is measured from the beginning of write to the end of write.
2. tCW is measured from the CS₁ going low or CS₂ going high to the end of write.
3. tAS is measured from the address valid to the beginning of write.
4. tWR is measured from the end of write to the address change. tWR applied in case a write ends as $\overline{CS_1}$ or $\overline{WE}$ going high tWR2 applied in case a write ends as CS₂ going to low.

DATA RETENTION WAVE FORM

CS₁ controlled



CS₂ controlled



CMOS SRAM

32 DUAL INLINE PACKAGE (600mil)

Technical drawing of a rectangular component, likely a PCB or a similar electronic component, showing dimensions and tolerances.

Top View Dimensions:

- Overall width: 13.60 ± 0.20 / 0.535 ± 0.008
- Overall height: 42.31 / 1.666 MAX
- Internal width: 41.91 ± 0.20 / 1.650 ± 0.008
- Pin pitch (bottom): 0.46 ± 0.10 / 0.018 ± 0.004
- Pin pitch (top): 0.18 ± 0.10 / 0.060 ± 0.004
- Pin width (bottom): 1.52 ± 0.10 / 0.060 ± 0.004
- Pin width (top): 2.54 / 0.100
- Pin length (bottom): 1.91 / 0.075
- Pin length (top): 0.38 / 0.015 MIN
- Pin spacing (bottom): 3.30 ± 0.30 / 0.130 ± 0.012
- Pin spacing (top): 5.08 / 0.200 MAX
- Pin spacing (middle): 3.81 ± 0.20 / 0.150 ± 0.008
- Pin spacing (bottom): 0.25 / 0.010 / $+0.10$ / -0.05 / -0.002

Side View Dimensions:

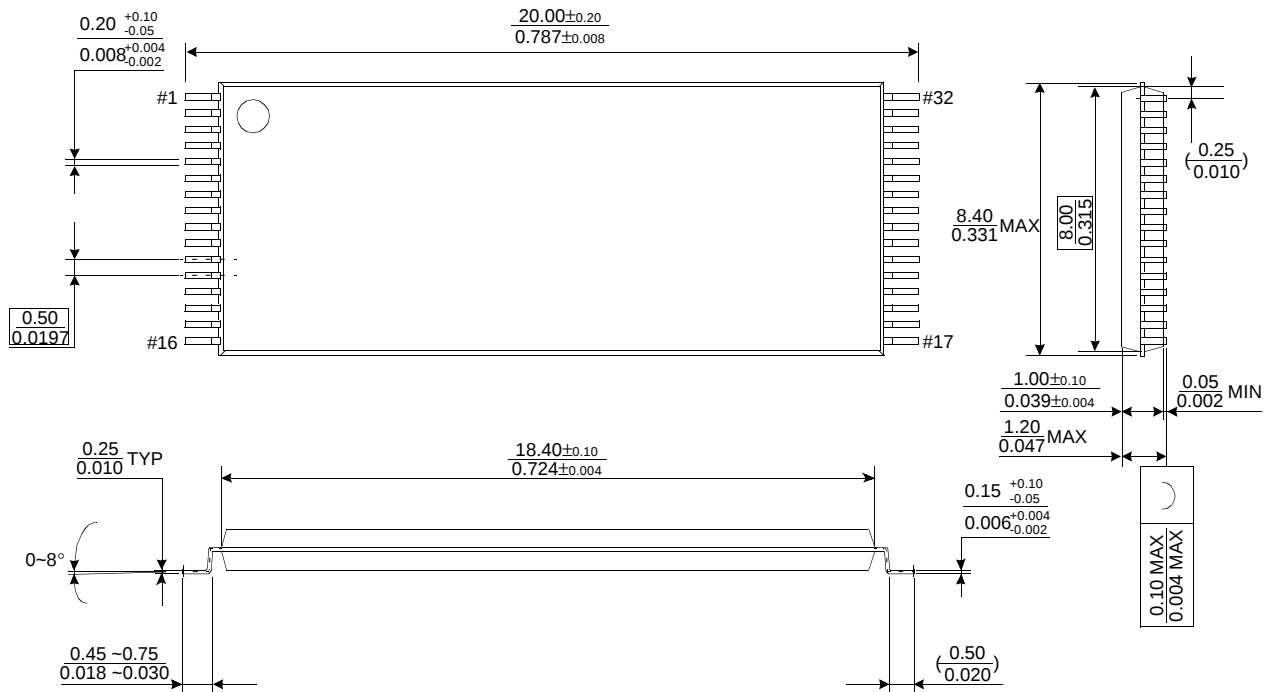
- Overall height: 15.24 / 0.600
- Pin angle: $0-15^\circ$

The drawing illustrates the mechanical specifications of a 32-pin DIP package. The top view shows a rectangular body with pins numbered 1 to 16 on one side and 17 to 32 on the other. Key dimensions include a body width of 14.12 ± 0.30 mm and a pin pitch of 2.54 ± 0.12 mm. The side view shows a maximum height of 20.87 mm and a pin height of 2.74 ± 0.20 mm. The end view shows a maximum thickness of 0.71 mm and a pin thickness of 0.05 mm. A detail view of the pin shows a diameter of 0.20 mm and a length of 13.34 mm. A note indicates a maximum lead angle of 0.10 mm.

PACKAGE DIMENSIONS

Units: millimeters(inches)

32 PIN THIN SMALL OUTLINE PACKAGE TYPE I (0820F)



32 THIN SMALL OUTLINE PACKAGE TYPE I (0820R)

